

AFE4960 用于临床可穿戴设备的双通道 ECG、呼吸和起搏脉冲检测模拟前端 (AFE)

1 特性

- 支持心电图和呼吸阻抗测量；可配置为 2 通道 ECG 或 1 通道 ECG + 1 通道呼吸
- 可用于符合 IEC 60601-2-47:2012/(R)2016 和 IEC 60601-2-27:2011(R)2016 的系统
- 作为 2 通道 ECG 运行时为 222 μ A/通道
- 1 个通道上的集成起搏脉冲检测
- 支持 3 导联心电图，可通过并行操作两个或更多 AFE 扩展到 5 导联或更多
- 用于监测 SpO₂、心率和 PTT 的 PPG 信号链
- ECG 信号链：
 - 高达 2.048 kHz 的单通道 ECG 采集
 - 高达 1.36 kHz/通道的 2 通道 ECG 采集
 - RLD 输出通过第三电极设置人体偏置
 - 可编程 INA 增益为 2 (大概) 至 12
 - >1 G Ω 输入阻抗，CMRR > 100 dB
 - 输入噪声 (0.5 Hz 至 150 Hz)：INA 增益为 3 时为 13 μ Vpp；INA 增益为 12 时为 5 μ Vpp
 - 集成式 370 Hz 抗混叠低通滤波器
 - 持续导联开/关检测模式
 - 导联阻抗测量模式
- Bio-Z 信号链：
 - 在 30kHz 至 100kHz 的激励频率范围内测量生物阻抗
 - 正弦波激励或方波激励
 - 呼吸阻抗测量：2 k Ω 基线阻抗上的 45 m Ω -pp 噪声
- 双通道 ECG 通道：
 - Bio-Z 接收器，可配置为第 2 个 ECG 通道
- PPG 信号链
 - 支持采集多达 24 个 PPG 信号
 - 在每个相位内均可实现灵活的 4 个 LED、4 个 PD 分配
 - 高达 250 mA 的 8 位 LED 电流控制
 - 输入端的低噪声电流 DAC 以消除直流
 - 跨阻增益：3.7 k Ω 至 1 M Ω
 - 滤波以降低传感器光学噪声带宽
- 外部时钟和内部振荡器模式
- 采样深度为 128 的 FIFO，24 位字
- SPI™，I²C 接口：可通过引脚进行选择
- 2.6mm × 2.6mm DSBGA 封装，0.4mm 间距
- 电源：Rx：1.7V - 1.9V，I_O：1.7V - 1.9V，Tx：3.0-5.5V

2 应用

- 用于住院和门诊监测的无线贴片
- 用于心律失常检测的事件监视器
- 手持式 ECG 监护仪
- 便携式多导联 ECG
- 病人生命体征监控：动态心电图、事件、压力和远程医疗
- 通过同步 ECG、PPG 监测 SpO₂ 和心率以及基于 PTT 的血压

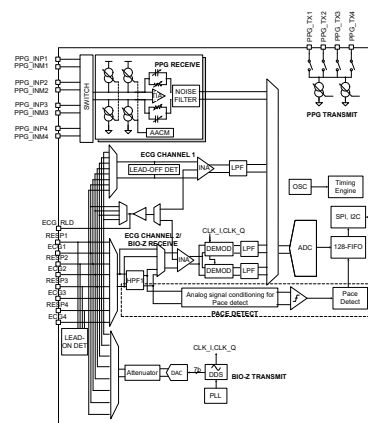
3 说明

AFE4960P 支持同步采集 ECG、PPG 和生物阻抗信号。PPG 信号链由 LED 电流驱动器和可检测来自 PD 的信号接收器构成。AFE 可配置为双通道 ECG 接收器或单通道 ECG 接收器和一个呼吸阻抗通道。AFE 信号链可以灵活地连接至最多 4 个电极。AFE 具有交流和直流导联偏置和导联开/关检测功能。一个通道支持起搏器脉冲检测。所有信号链输出都由单个 ADC 在明确定义的时隙中转换，并作为 24 位字存储在 128 样本 FIFO 中，可以使用 SPI 或 I²C 界面读出。AFE4960P 可用于实现具有 SpO₂ 的 3 导联 ECG 系统。

器件信息

器件型号	封装 ⁽¹⁾	封装尺寸 (标称值)
AFE4960P	DSBGA (YBG 36)	2.6 mm x 2.6 mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



方框图



Table of Contents

1 特性	1	5.2 接收文档更新通知.....	3
2 应用	1	5.3 支持资源.....	3
3 说明	1	5.4 Trademarks.....	3
4 Revision History	2	5.5 Electrostatic Discharge Caution.....	3
5 Device and Documentation Support	3	5.6 术语表.....	3
5.1 Documentation Support.....	3	6 Mechanical, Packaging, and Orderable Information	3

4 Revision History

注：以前版本的页码可能与当前版本的页码不同

DATE	REVISION	NOTES
May 2022	*	Initial Release

5 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

5.1 Documentation Support

5.1.1 Related Documentation

5.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

5.3 支持资源

TI E2E™ [支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

5.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

5.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
AFE4960PYBGR	ACTIVE	DSBGA	YBG	36	3000	RoHS & Green	SAC396	Level-1-260C-UNLIM	-40 to 85	AFE4960P	Samples
AFE4960PYBGT	ACTIVE	DSBGA	YBG	36	250	RoHS & Green	SAC396	Level-1-260C-UNLIM	-40 to 85	AFE4960P	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

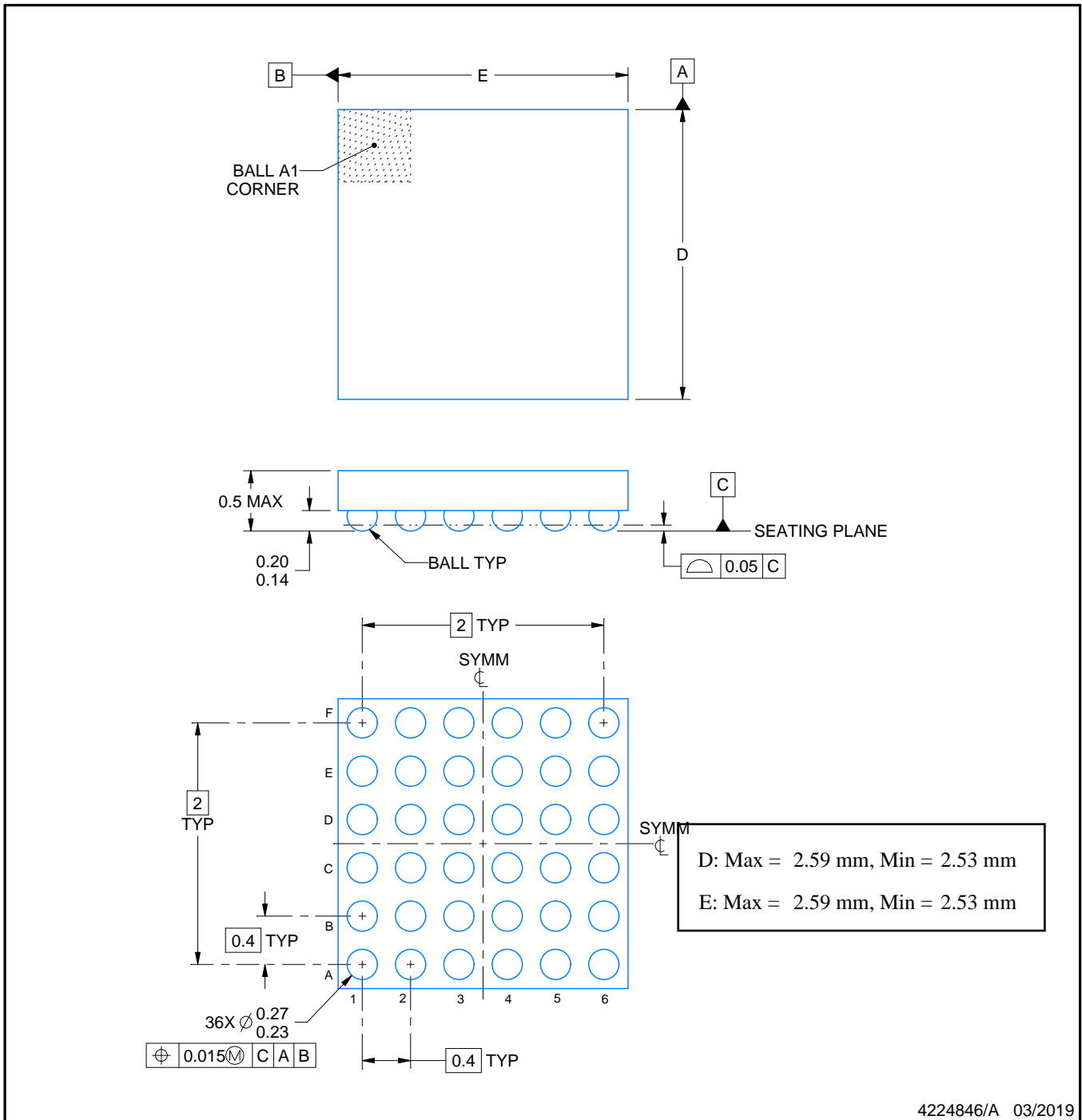
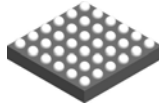
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



NOTES:

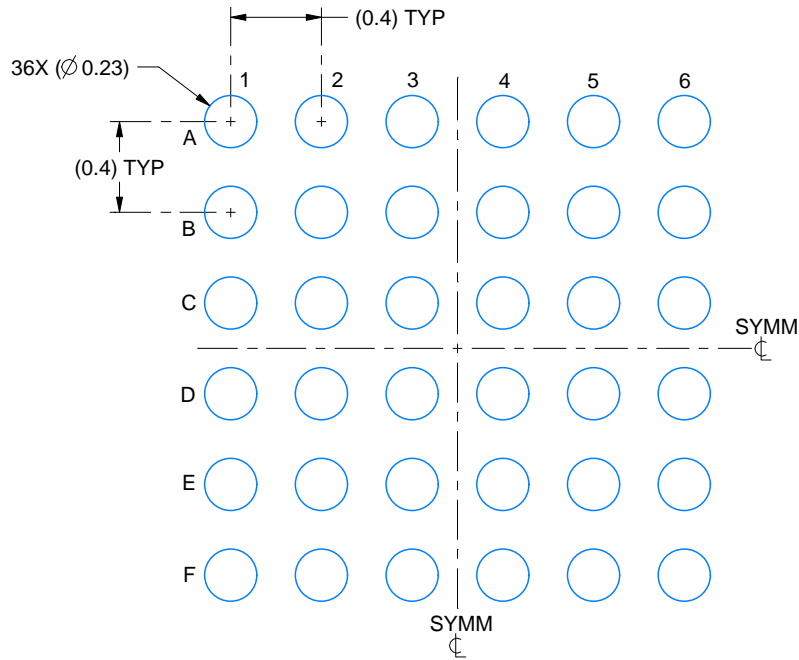
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

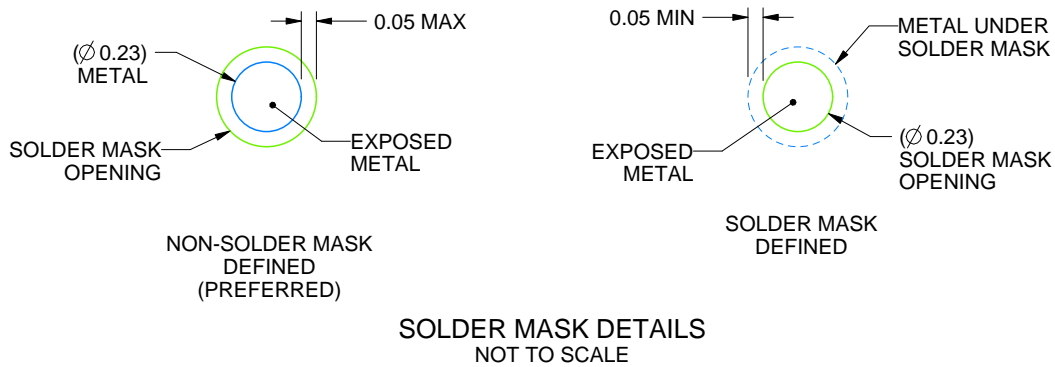
YBG0036

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 30X



SOLDER MASK DETAILS
NOT TO SCALE

4224846/A 03/2019

NOTES: (continued)

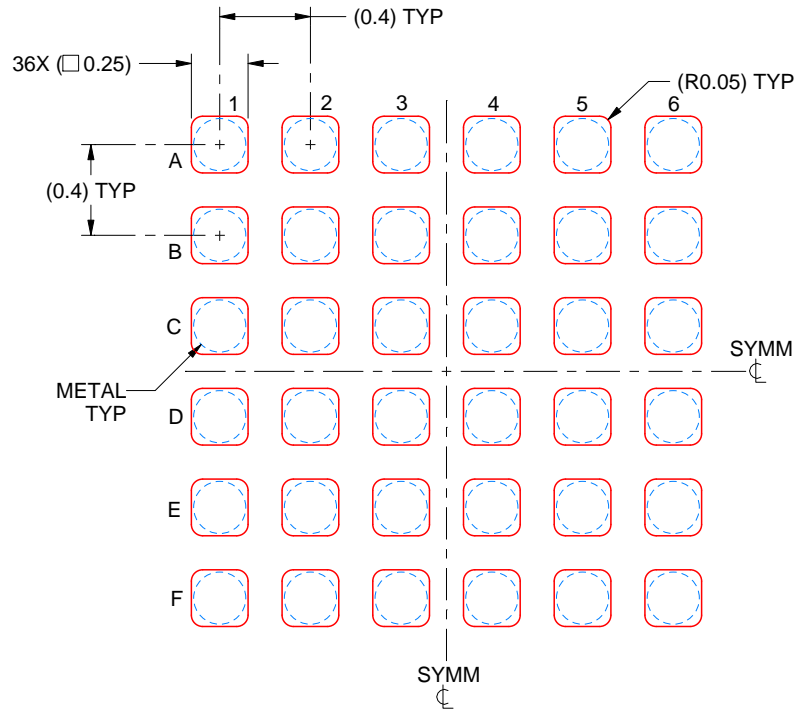
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

YBG0036

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE: 30X

4224846/A 03/2019

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

重要声明和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2022，德州仪器 (TI) 公司